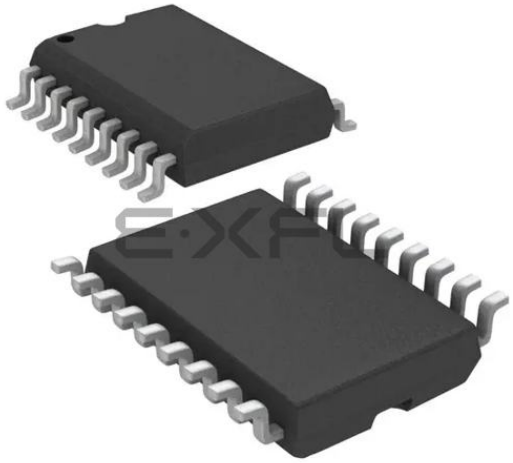


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	896B (512 x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	96 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc620at-04-so

2.0 PIC16C62X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in the PIC16C62X Product Identification System section at the end of this data sheet. When placing orders, please use this page of the data sheet to specify the correct part number.

2.1 UV Erasable Devices

The UV erasable version, offered in CERDIP package, is optimal for prototype development and pilot programs. This version can be erased and reprogrammed to any of the Oscillator modes.

Microchip's PICSTART® and PRO MATE® programmers both support programming of the PIC16C62X.

Note:	Microchip does not recommend code protecting windowed devices.

2.2 One-Time-Programmable (OTP) Devices

The availability of OTP devices is especially useful for customers who need the flexibility for frequent code updates and small volume applications. In addition to the program memory, the configuration bits must also be programmed.

2.3 Quick-Turnaround-Production (QTP) Devices

Microchip offers a QTP programming service for factory production orders. This service is made available for users who chose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices, but with all EPROM locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your Microchip Technology sales office for more details.

2.4 Serialized Quick-Turnaround-Production℠ (SQTP℠) Devices

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential.

Serial programming allows each device to have a unique number, which can serve as an entry-code, password or ID number.

NOTES:

3.1 Clocking Scheme/Instruction Cycle

The clock input (OSC1/CLKIN pin) is internally divided by four to generate four non-overlapping quadrature clocks namely Q1, Q2, Q3 and Q4. Internally, the program counter (PC) is incremented every Q1, the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow is shown in Figure 3-2.

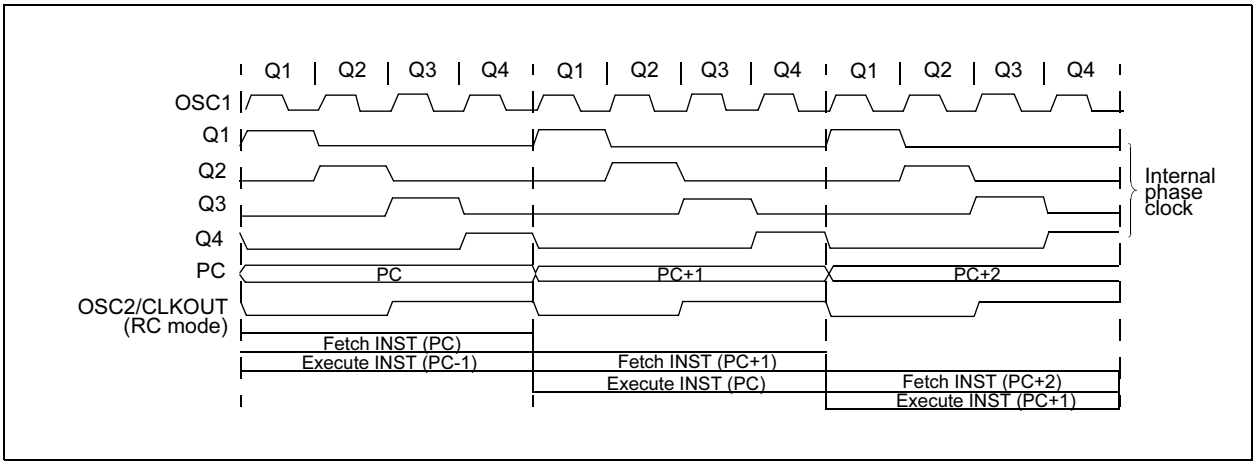
3.2 Instruction Flow/Pipelining

An "Instruction Cycle" consists of four Q cycles (Q1, Q2, Q3 and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g., `GOTO`) then two cycles are required to complete the instruction (Example 3-1).

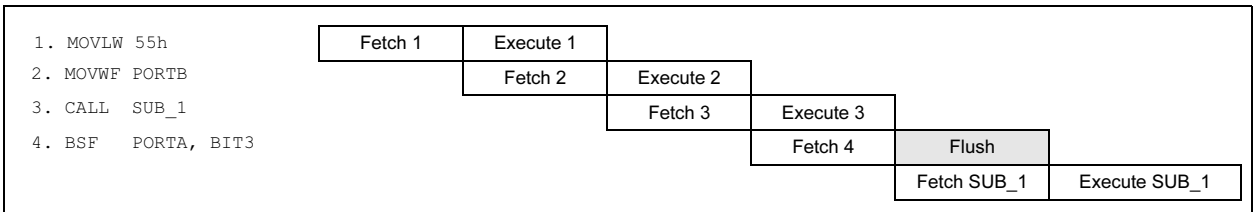
A fetch cycle begins with the program counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the "Instruction Register (IR)" in cycle Q1. This instruction is then decoded and executed during the Q2, Q3 and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 3-2: CLOCK/INSTRUCTION CYCLE



EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW



Note: All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is "flushed" from the pipeline, while the new instruction is being fetched and then executed.

4.2.2.1 STATUS Register

The STATUS register, shown in Register 4-1, contains the arithmetic status of the ALU, the RESET status and the bank select bits for data memory.

The STATUS register can be the destination for any instruction, like any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the $\overline{TO}$ and $\overline{PD}$ bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, `CLRF STATUS` will clear the upper-three bits and set the Z bit. This leaves the STATUS register as `000uu1uu` (where `u` = unchanged).

It is recommended, therefore, that only `BCF`, `BSF`, `SWAPF` and `MOVWF` instructions are used to alter the STATUS register, because these instructions do not affect any STATUS bit. For other instructions not affecting any STATUS bits, see the "Instruction Set Summary".

Note 1: The IRP and RP1 bits (STATUS<7:6>) are not used by the PIC16C62X and should be programmed as '0'. Use of these bits as general purpose R/W bits is NOT recommended, since this may affect upward compatibility with future products.

2: The C and DC bits operate as a $\overline{\text{Borrow}}$ and Digit $\overline{\text{Borrow}}$ out bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

REGISTER 4-1: STATUS REGISTER (ADDRESS 03H OR 83H)

Reserved	Reserved	R/W-0	R-1	R-1	R/W-x	R/W-x	R/W-x
IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C
bit 7							bit 0

bit 7 **IRP:** Register Bank Select bit (used for indirect addressing)
`1` = Bank 2, 3 (100h - 1FFh)
`0` = Bank 0, 1 (00h - FFh)
The IRP bit is reserved on the PIC16C62X; always maintain this bit clear.

bit 6-5 **RP<1:0>**: Register Bank Select bits (used for direct addressing)
`01` = Bank 1 (80h - FFh)
`00` = Bank 0 (00h - 7Fh)
Each bank is 128 bytes. The RP1 bit is reserved on the PIC16C62X; always maintain this bit clear.

bit 4 **$\overline{TO}$**: Time-out bit
`1` = After power-up, `CLRWDT` instruction, or `SLEEP` instruction
`0` = A WDT time-out occurred

bit 3 **$\overline{PD}$**: Power-down bit
`1` = After power-up or by the `CLRWDT` instruction
`0` = By execution of the `SLEEP` instruction

bit 2 **Z**: Zero bit
`1` = The result of an arithmetic or logic operation is zero
`0` = The result of an arithmetic or logic operation is not zero

bit 1 **DC**: Digit carry/$\overline{\text{borrow}}$ bit (`ADDWF, ADDLW,SUBLW,SUBWF` instructions)(for $\overline{\text{borrow}}$ the polarity is reversed)
`1` = A carry-out from the 4th low order bit of the result occurred
`0` = No carry-out from the 4th low order bit of the result

bit 0 **C**: Carry/$\overline{\text{borrow}}$ bit (`ADDWF, ADDLW,SUBLW,SUBWF` instructions)
`1` = A carry-out from the Most Significant bit of the result occurred
`0` = No carry-out from the Most Significant bit of the result occurred

Note: For $\overline{\text{borrow}}$ the polarity is reversed. A subtraction is executed by adding the two's complement of the second operand. For rotate (`RRF, RLF`) instructions, this bit is loaded with either the high or low order bit of the source register.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

4.2.2.4 PIE1 Register

This register contains the individual enable bit for the comparator interrupt.

REGISTER 4-4: PIE1 REGISTER (ADDRESS 8CH)

U-0	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0
—	CMIE	—	—	—	—	—	—
bit 7							bit 0

bit 7 **Unimplemented:** Read as '0'

bit 6 **CMIE**: Comparator Interrupt Enable bit
1 = Enables the Comparator interrupt
0 = Disables the Comparator interrupt

bit 5-0 **Unimplemented**: Read as '0'

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

4.2.2.5 PIR1 Register

This register contains the individual flag bit for the comparator interrupt.

Note:	Interrupt flag bits get set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

REGISTER 4-5: PIR1 REGISTER (ADDRESS 0CH)

U-0	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0
—	CMIF	—	—	—	—	—	—
bit 7							bit 0

bit 7 **Unimplemented:** Read as '0'

bit 6 **CMIF**: Comparator Interrupt Flag bit
1 = Comparator input has changed
0 = Comparator input has not changed

bit 5-0 **Unimplemented**: Read as '0'

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

4.2.2.6 PCON Register

The PCON register contains flag bits to differentiate between a Power-on Reset, an external MCLR Reset, WDT Reset or a Brown-out Reset.

Note:	BOR is unknown on Power-on Reset. It must then be set by the user and checked on subsequent RESETS to see if BOR is cleared, indicating a brown-out has occurred. The BOR STATUS bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (by programming BODEN bit in the Configuration word).

REGISTER 4-6: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	POR	BOR
bit 7							bit 0

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **POR**: Power-on Reset STATUS bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0 **BOR**: Brown-out Reset STATUS bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

4.4 Indirect Addressing, INDF and FSR Registers

The INDF register is not a physical register. Addressing the INDF register will cause indirect addressing.

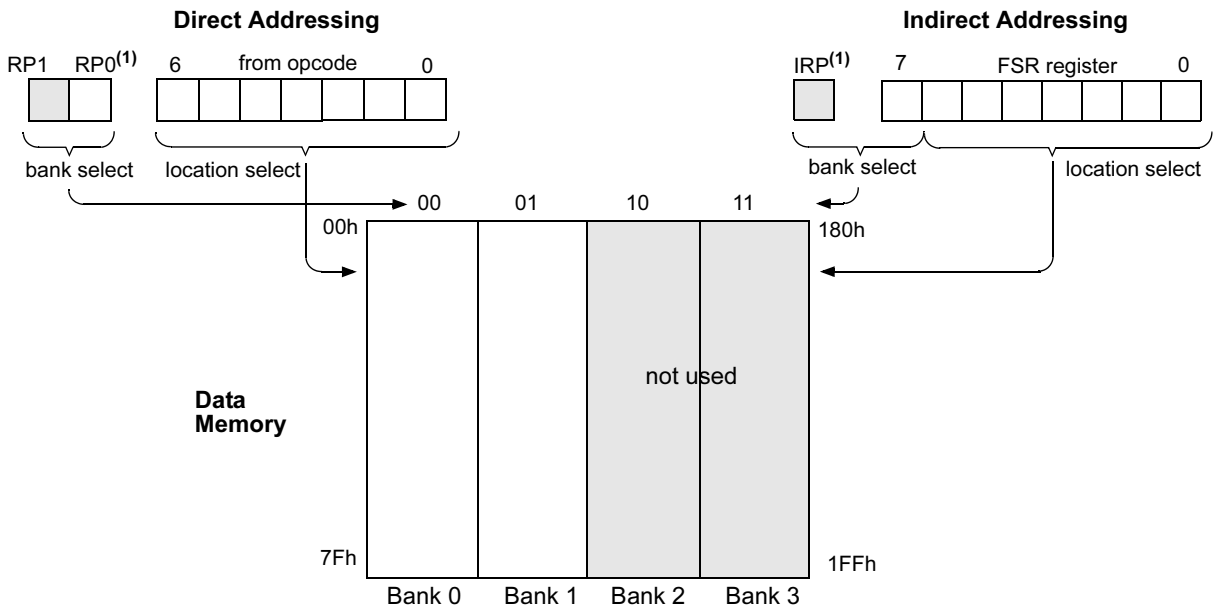
Indirect addressing is possible by using the INDF register. Any instruction using the INDF register actually accesses data pointed to by the File Select Register (FSR). Reading INDF itself indirectly will produce 00h. Writing to the INDF register indirectly results in a no-operation (although STATUS bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 4-9. However, IRP is not used in the PIC16C62X.

A simple program to clear RAM location 20h-7Fh using indirect addressing is shown in Example 4-1.

EXAMPLE 4-1: INDIRECT ADDRESSING

```
      movlw   0x20       ;initialize pointer
      movwf   FSR        ;to RAM
NEXT  clrf    INDF       ;clear INDF register
      incf    FSR        ;inc pointer
      btfss   FSR,7      ;all done?
      goto    NEXT       ;no clear next
                         ;yes continue
CONTINUE:
```

FIGURE 4-9: DIRECT/INDIRECT ADDRESSING PIC16C62X



For memory map detail see (Figure 4-4, Figure 4-5, Figure 4-6 and Figure 4-7).

Note 1: The RP1 and IRP bits are reserved; always maintain these bits clear.

6.0 TIMER0 MODULE

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
- Interrupt on overflow from FFh to 00h
- Edge select for external clock

Figure 6-1 is a simplified block diagram of the Timer0 module.

Timer mode is selected by clearing the T0CS bit (OPTION<5>). In Timer mode, the TMR0 will increment every instruction cycle (without prescaler). If Timer0 is written, the increment is inhibited for the following two cycles (Figure 6-2 and Figure 6-3). The user can work around this by writing an adjusted value to TMR0.

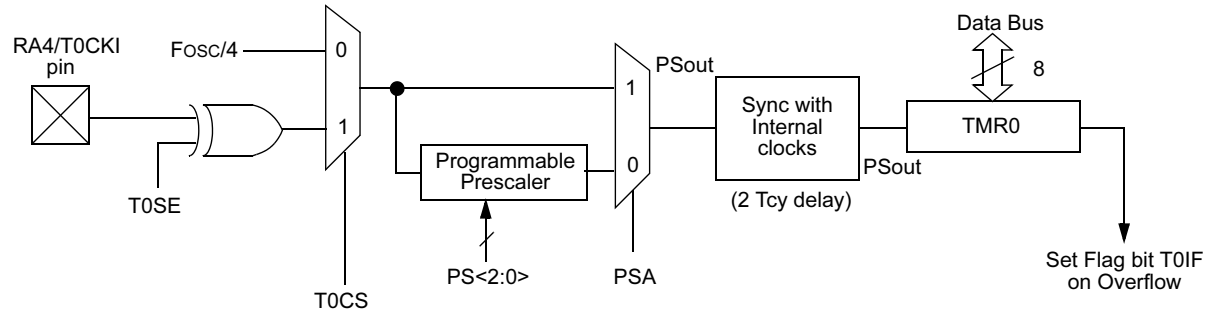
Counter mode is selected by setting the T0CS bit. In this mode, Timer0 will increment either on every rising or falling edge of pin RA4/T0CKI. The incrementing edge is determined by the source edge (T0SE) control bit (OPTION<4>). Clearing the T0SE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 6.2.

The prescaler is shared between the Timer0 module and the Watchdog Timer. The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale value of 1:2, 1:4, ..., 1:256 are selectable. Section 6.3 details the operation of the prescaler.

6.1 TIMER0 Interrupt

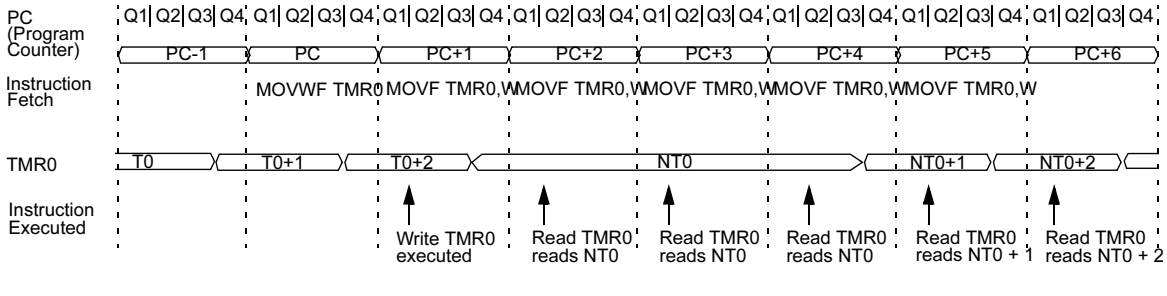
Timer0 interrupt is generated when the TMR0 register timer/counter overflows from FFh to 00h. This overflow sets the T0IF bit. The interrupt can be masked by clearing the T0IE bit (INTCON<5>). The T0IF bit (INTCON<2>) must be cleared in software by the Timer0 module interrupt service routine before re-enabling this interrupt. The Timer0 interrupt cannot wake the processor from SLEEP, since the timer is shut off during SLEEP. See Figure 6-4 for Timer0 interrupt timing.

FIGURE 6-1: TIMER0 BLOCK DIAGRAM



Note 1: Bits T0SE, T0CS, PS2, PS1, PS0 and PSA are located in the OPTION register.
2: The prescaler is shared with Watchdog Timer (Figure 6-6).

FIGURE 6-2: TIMER0 (TMR0) TIMING: INTERNAL CLOCK/NO PRESCALER



7.0 COMPARATOR MODULE

The comparator module contains two analog comparators. The inputs to the comparators are multiplexed with the RA0 through RA3 pins. The On-Chip Voltage Reference (Section 8.0) can also be an input to the comparators.

The CMCON register, shown in Register 7-1, controls the comparator input and output multiplexers. A block diagram of the comparator is shown in Figure 7-1.

REGISTER 7-1: CMCON REGISTER (ADDRESS 1Fh)

R-0	R-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
C2OUT	C1OUT	—	—	CIS	CM2	CM1	CM0
bit 7							bit 0

bit 7 **C2OUT**: Comparator 2 output
1 = C2 VIN+ > C2 VIN-
0 = C2 VIN+ < C2 VIN-

bit 6 **C1OUT**: Comparator 1 output
1 = C1 VIN+ > C1 VIN-
0 = C1 VIN+ < C1 VIN-

bit 5-4 **Unimplemented:** Read as '0'

bit 3 **CIS**: Comparator Input Switch
When CM<2:0>: = 001:
1 = C1 VIN- connects to RA3
0 = C1 VIN- connects to RA0
When CM<2:0> = 010:
1 = C1 VIN- connects to RA3
C2 VIN- connects to RA2
0 = C1 VIN- connects to RA0
C2 VIN- connects to RA1

bit 2-0 **CM<2:0>**: Comparator mode.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

9.2.3 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator can be used or a simple oscillator circuit with TTL gates can be built. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used; one with series resonance or one with parallel resonance.

Figure 9-3 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180° phase shift that a parallel oscillator requires. The 4.7 kΩ resistor provides the negative feedback for stability. The 10 kΩ potentiometers bias the 74AS04 in the linear region. This could be used for external oscillator designs.

FIGURE 9-3: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

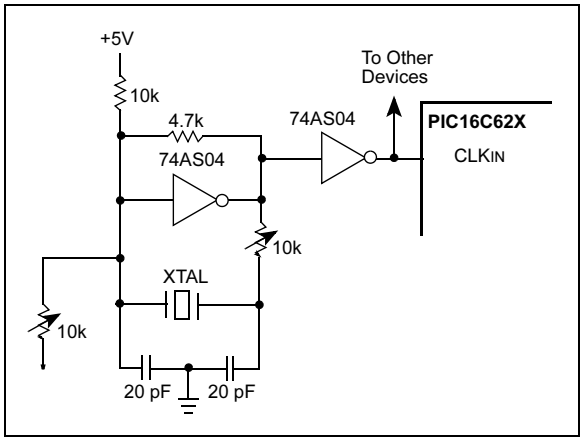
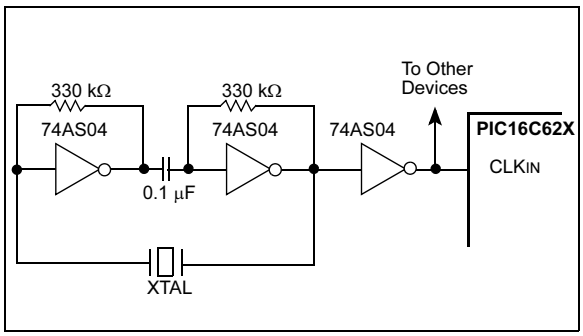


Figure 9-4 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180° phase shift in a series resonant oscillator circuit. The 330 kΩ resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 9-4: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



9.2.4 RC OSCILLATOR

For timing insensitive applications the "RC" device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low CEXT values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 9-5 shows how the R/C combination is connected to the PIC16C62X. For REXT values below 2.2 kΩ, the oscillator operation may become unstable or stop completely. For very high REXT values (e.g., 1 MΩ), the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend to keep REXT between 3 kΩ and 100 kΩ.

Although the oscillator will operate with no external capacitor (CEXT = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

See Section 13.0 for RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

See Section 13.0 for variation of oscillator frequency due to VDD for given REXT/CEXT values, as well as frequency variation due to operating temperature for given R, C and VDD values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin, and can be used for test purposes or to synchronize other logic (Figure 3-2 for waveform).

FIGURE 9-5: RC OSCILLATOR MODE

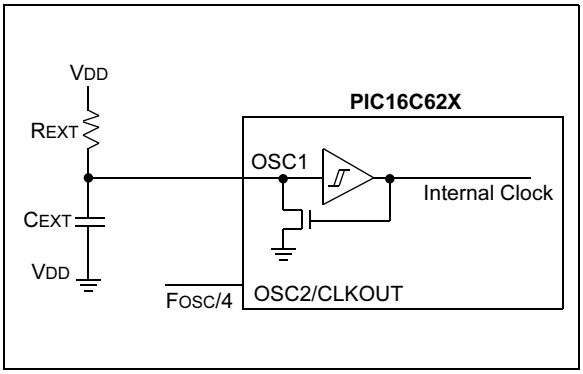
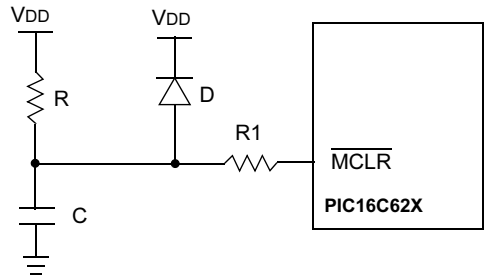


FIGURE 9-11: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)

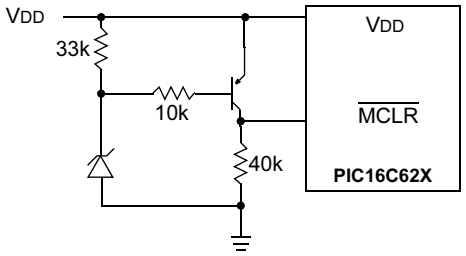


Note 1: External Power-on Reset circuit is required only if VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device's electrical specification.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into MCLR from external capacitor C in the event of MCLR/VPP pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

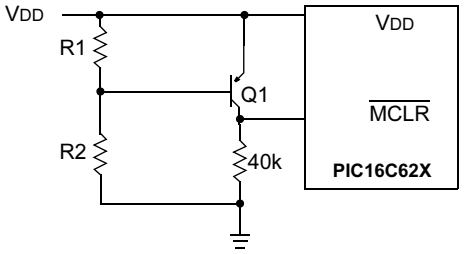
FIGURE 9-12: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 1



Note 1: This circuit will activate RESET when VDD goes below (Vz + 0.7V) where Vz = Zener voltage.

2: Internal Brown-out Reset circuitry should be disabled when using this circuit.

FIGURE 9-13: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 2



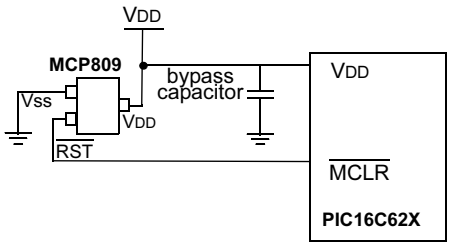
Note 1: This brown-out circuit is less expensive, albeit less accurate. Transistor Q1 turns off when VDD is below a certain level such that:

$$V_{DD} \times \frac{R1}{R1 + R2} = 0.7V$$

2: Internal Brown-out Reset should be disabled when using this circuit.

3: Resistors should be adjusted for the characteristics of the transistor.

FIGURE 9-14: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 3



This brown-out protection circuit employs Microchip Technology's MCP809 microcontroller supervisor. The MCP8XX and MCP1XX families of supervisors provide push-pull and open collector outputs with both high and low active RESET pins. There are 7 different trip point selections to accommodate 5V and 3V systems.

9.5.1 RB0/INT INTERRUPT

External interrupt on RB0/INT pin is edge triggered, either rising if INTEDG bit (OPTION<6>) is set, or falling, if INTEDG bit is clear. When a valid edge appears on the RB0/INT pin, the INTF bit (INTCON<1>) is set. This interrupt can be disabled by clearing the INTE control bit (INTCON<4>). The INTF bit must be cleared in software in the interrupt service routine before re-enabling this interrupt. The RB0/INT interrupt can wake-up the processor from SLEEP, if the INTE bit was set prior to going into SLEEP. The status of the GIE bit decides whether or not the processor branches to the interrupt vector following wake-up. See Section 9.8 for details on SLEEP and Figure 9-18 for timing of wake-up from SLEEP through RB0/INT interrupt.

9.5.2 TMR0 INTERRUPT

An overflow (FFh → 00h) in the TMR0 register will set the T0IF (INTCON<2>) bit. The interrupt can be enabled/disabled by setting/clearing T0IE (INTCON<5>) bit. For operation of the Timer0 module, see Section 6.0.

9.5.3 PORTB INTERRUPT

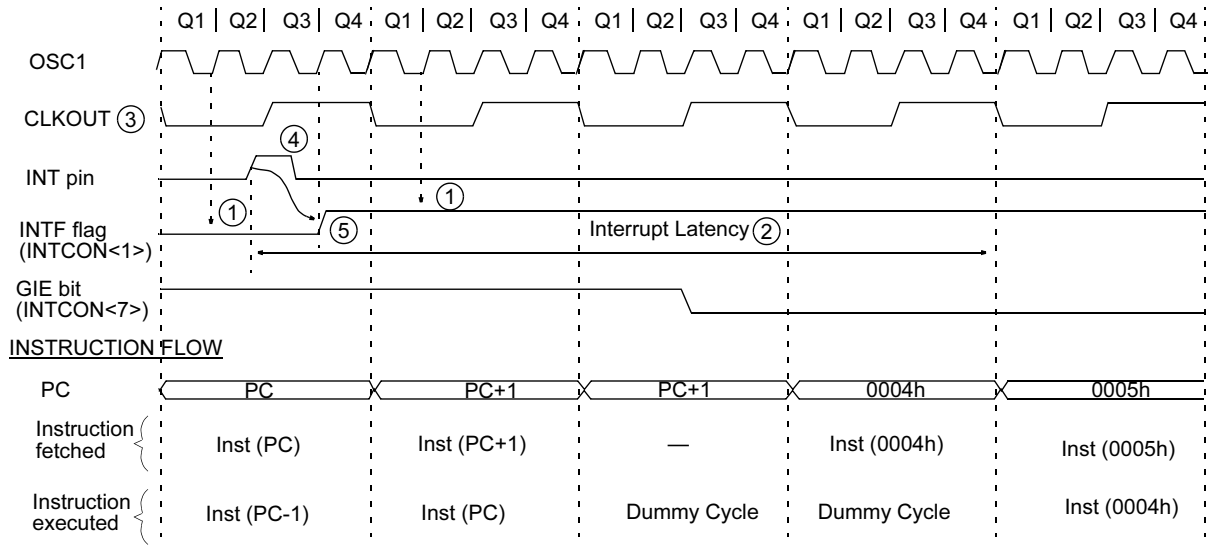
An input change on PORTB <7:4> sets the RBIF (INTCON<0>) bit. The interrupt can be enabled/disabled by setting/clearing the RBIE (INTCON<4>) bit. For operation of PORTB (Section 5.2).

Note:	If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set.

9.5.4 COMPARATOR INTERRUPT

See Section 7.6 for complete description of comparator interrupts.

FIGURE 9-16: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Asynchronous interrupt latency = 3-4 TCY. Synchronous latency = 3 TCY, where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a two-cycle instruction.

3: CLKOUT is available only in RC Oscillator mode.

4: For minimum width of INT pulse, refer to AC specs.

5: INTF is enabled to be set anytime during the Q4-Q1 cycles.

TABLE 9-6: SUMMARY OF INTERRUPT REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other RESETS(1)
0Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	CMIF	—	—	—	—	—	—	-0-- ----	-0-- ----
8Ch	PIE1	—	CMIE	—	—	—	—	—	—	-0-- ----	-0-- ----

Note 1: Other (non Power-up) Resets include $\overline{MCLR}$ Reset, Brown-out Reset and Watchdog Timer Reset during normal operation.

9.6 Context Saving During Interrupts

During an interrupt, only the return PC value is saved on the stack. Typically, users may wish to save key registers during an interrupt (e.g., W register and STATUS register). This will have to be implemented in software.

Example 9-3 stores and restores the STATUS and W registers. The user register, W_TEMP, must be defined in both banks and must be defined at the same offset from the bank base address (i.e., W_TEMP is defined at 0x20 in Bank 0 and it must also be defined at 0xA0 in Bank 1). The user register, STATUS_TEMP, must be defined in Bank 0. The Example 9-3:

- Stores the W register
- Stores the STATUS register in Bank 0
- Executes the ISR code
- Restores the STATUS (and bank select bit register)
- Restores the W register

EXAMPLE 9-3: SAVING THE STATUS AND W REGISTERS IN RAM

```
MOVWF   W_TEMP          ;copy W to temp register,
                        ;could be in either bank
SWAPF   STATUS,W        ;swap status to be saved
                        into W
BCF     STATUS,RP0      ;change to bank 0 regardless
                        ;of current bank
MOVWF   STATUS_TEMP     ;save status to bank 0
                        ;register
:
:       (ISR)
:
SWAPF   STATUS_TEMP,    ;swap STATUS_TEMP register
        W               ;into W, sets bank to origi-
                        nal
                        ;state
MOVWF   STATUS          ;move W into STATUS register
SWAPF   W_TEMP,F        ;swap W_TEMP
SWAPF   W_TEMP,W        ;swap W_TEMP into W
```

RLF **Rotate Left f through Carry**

Syntax: [*label*] RLF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

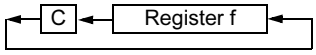
Operation: See description below

Status Affected: C

Encoding:

00	1101	dfff	ffff

Description: The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is stored back in register 'f'.



Words: 1

Cycles: 1

Example

```
RLF     REG1,0
```

Before Instruction

```
REG1    =   1110 0110
C       =   0
```

After Instruction

```
REG1    =   1110 0110
W       =   1100 1100
C       =   1
```

RRF **Rotate Right f through Carry**

Syntax: [*label*] RRF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

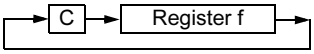
Operation: See description below

Status Affected: C

Encoding:

00	1100	dfff	ffff

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.



Words: 1

Cycles: 1

Example

```
RRF         REG1,
            0
```

Before Instruction

```
REG1    =   1110 0110
C       =   0
```

After Instruction

```
REG1    =   1110 0110
W       =   0111 0011
C       =   0
```

SLEEP

Syntax: [*label*] SLEEP

Operands: None

Operation: 00h → WDT,
0 → WDT prescaler,
1 → $\overline{TO}$,
0 → $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

00	0000	0110	0011

Description: The power-down STATUS bit, $\overline{PD}$ is cleared. Time-out STATUS bit, $\overline{TO}$ is set. Watch-dog Timer and its prescaler are cleared.
The processor is put into SLEEP mode with the oscillator stopped. See Section 9.8 for more details.

Words: 1

Cycles: 1

Example:

```
SLEEP
```

11.0 DEVELOPMENT SUPPORT

The PICmicro® microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
  - MPLAB® IDE Software
- Assemblers/Compilers/Linkers
  - MPASM™ Assembler
  - MPLAB C17 and MPLAB C18 C Compilers
  - MPLINK™ Object Linker/ MPLIB™ Object Librarian
  - MPLAB C30 C Compiler
  - MPLAB ASM30 Assembler/Linker/Library
- Simulators
  - MPLAB SIM Software Simulator
  - MPLAB dsPIC30 Software Simulator
- Emulators
  - MPLAB ICE 2000 In-Circuit Emulator
  - MPLAB ICE 4000 In-Circuit Emulator
- In-Circuit Debugger
  - MPLAB ICD 2
- Device Programmers
  - PRO MATE® II Universal Device Programmer
  - PICSTART® Plus Development Programmer
- Low Cost Demonstration Boards
  - PICDEM™ 1 Demonstration Board
  - PICDEM.net™ Demonstration Board
  - PICDEM 2 Plus Demonstration Board
  - PICDEM 3 Demonstration Board
  - PICDEM 4 Demonstration Board
  - PICDEM 17 Demonstration Board
  - PICDEM 18R Demonstration Board
  - PICDEM LIN Demonstration Board
  - PICDEM USB Demonstration Board
- Evaluation Kits
  - KEELOQ®
  - PICDEM MSC
  - microID®
  - CAN
  - PowerSmart®
  - Analog

11.1 MPLAB Integrated Development Environment Software

The MPLAB IDE software brings an ease of software development previously unseen in the 8/16-bit microcontroller market. The MPLAB IDE is a Windows® based application that contains:

- An interface to debugging tools
  - simulator
  - programmer (sold separately)
  - emulator (sold separately)
  - in-circuit debugger (sold separately)
- A full-featured editor with color coded context
- A multiple project manager
- Customizable data windows with direct edit of contents
- High level source code debugging
- Mouse over variable inspection
- Extensive on-line help

The MPLAB IDE allows you to:

- Edit your source files (either assembly or C)
- One touch assemble (or compile) and download to PICmicro emulator and simulator tools (automatically updates all project information)
- Debug using:
  - source files (assembly or C)
  - absolute listing file (mixed assembly and C)
  - machine code

MPLAB IDE supports multiple debugging tools in a single development paradigm, from the cost effective simulators, through low cost in-circuit debuggers, to full-featured emulators. This eliminates the learning curve when upgrading to tools with increasing flexibility and power.

11.2 MPASM Assembler

The MPASM assembler is a full-featured, universal macro assembler for all PICmicro MCUs.

The MPASM assembler generates relocatable object files for the MPLINK object linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM assembler features include:

- Integration into MPLAB IDE projects
- User defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

11.20 PICDEM 18R PIC18C601/801 Demonstration Board

The PICDEM 18R demonstration board serves to assist development of the PIC18C601/801 family of Microchip microcontrollers. It provides hardware implementation of both 8-bit Multiplexed/De-multiplexed and 16-bit Memory modes. The board includes 2 Mb external FLASH memory and 128 Kb SRAM memory, as well as serial EEPROM, allowing access to the wide range of memory types supported by the PIC18C601/801.

11.21 PICDEM LIN PIC16C43X Demonstration Board

The powerful LIN hardware and software kit includes a series of boards and three PICmicro microcontrollers. The small footprint PIC16C432 and PIC16C433 are used as slaves in the LIN communication and feature on-board LIN transceivers. A PIC16F874 FLASH microcontroller serves as the master. All three microcontrollers are programmed with firmware to provide LIN bus communication.

11.22 PICkit™ 1 FLASH Starter Kit

A complete "development system in a box", the PICkit FLASH Starter Kit includes a convenient multi-section board for programming, evaluation, and development of 8/14-pin FLASH PIC® microcontrollers. Powered via USB, the board operates under a simple Windows GUI. The PICkit 1 Starter Kit includes the user's guide (on CD ROM), PICkit 1 tutorial software and code for various applications. Also included are MPLAB® IDE (Integrated Development Environment) software, software and hardware "Tips 'n Tricks for 8-pin FLASH PIC® Microcontrollers" Handbook and a USB Interface Cable. Supports all current 8/14-pin FLASH PIC microcontrollers, as well as many future planned devices.

11.23 PICDEM USB PIC16C7X5 Demonstration Board

The PICDEM USB Demonstration Board shows off the capabilities of the PIC16C745 and PIC16C765 USB microcontrollers. This board provides the basis for future USB products.

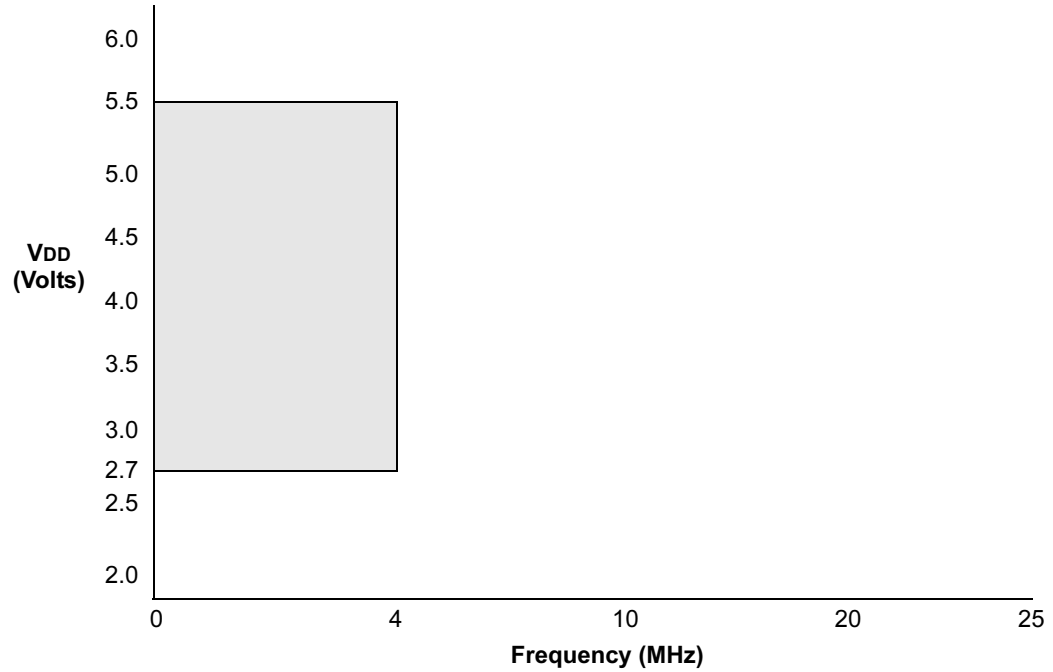
11.24 Evaluation and Programming Tools

In addition to the PICDEM series of circuits, Microchip has a line of evaluation kits and demonstration software for these products.

- KEELOQ evaluation and programming tools for Microchip's HCS Secure Data Products
- CAN developers kit for automotive network applications
- Analog design boards and filter design software
- PowerSmart battery charging evaluation/ calibration kits
- IrDA® development kit
- microID development and rfLab™ development software
- SEEVAL® designer kit for memory evaluation and endurance calculations
- PICDEM MSC demo boards for Switching mode power supply, high power IR driver, delta sigma ADC, and flow rate sensor

Check the Microchip web page and the latest Product Line Card for the complete list of demonstration and evaluation kits.

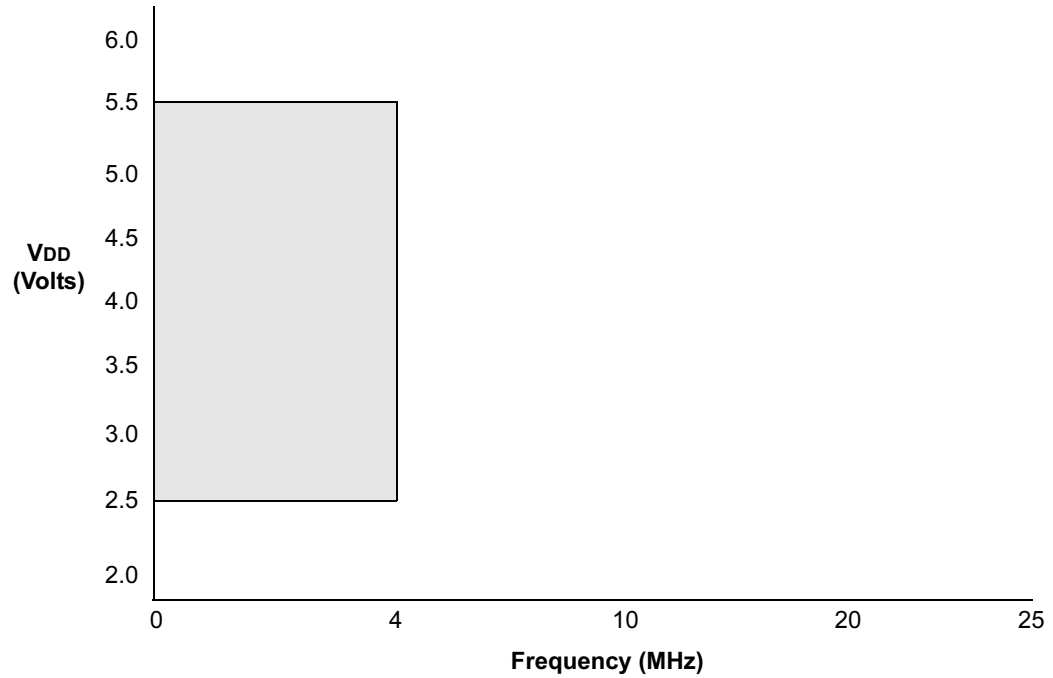
FIGURE 12-5: PIC16LC620A/LC621A/LC622A VOLTAGE-FREQUENCY GRAPH, -40°C ≤ TA ≤ 0°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

FIGURE 12-6: PIC16LC620A/LC621A/LC622A VOLTAGE-FREQUENCY GRAPH, 0°C ≤ TA ≤ +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.

2: The maximum rated speed of the part limits the permissible combinations of voltage and frequency. Please reference the Product Identification System section for the maximum rated speed of the parts.

12.2 DC Characteristics: PIC16C62XA-04 (Commercial, Industrial, Extended) PIC16C62XA-20 (Commercial, Industrial, Extended) PIC16LC62XA-04 (Commercial, Industrial, Extended) (CONT.)

PIC16C62XA			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
PIC16LC62XA			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and -40°C ≤ TA ≤ +125°C for extended				
Param. No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D010	IDD	Supply Current(2, 4)	—	1.2	2.0	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, **(Note 4)***
			—	0.4	1.2	mA	FOSC = 4 MHz, VDD = 3.0V, WDT disabled, XT mode, **(Note 4)***
			—	1.0	2.0	mA	FOSC = 10 MHz, VDD = 3.0V, WDT disabled, HS mode, **(Note 6)**
			—	4.0	6.0	mA	FOSC = 20 MHz, VDD = 4.5V, WDT disabled, HS mode
			—	4.0	7.0	mA	FOSC = 20 MHz, VDD = 5.5V, WDT disabled*, HS mode
			—	35	70	µA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP mode
D010	IDD	Supply Current(2)	—	1.2	2.0	mA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT mode, **(Note 4)***
			—	—	1.1	mA	FOSC = 4 MHz, VDD = 2.5V, WDT disabled, XT mode, **(Note 4)**
			—	35	70	µA	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode
D020	IPD	Power-down Current(3)	—	—	2.2	µA	VDD = 3.0V
			—	—	5.0	µA	VDD = 4.5V*
			—	—	9.0	µA	VDD = 5.5V
			—	—	15	µA	VDD = 5.5V Extended Temp.
D020	IPD	Power-down Current(3)	—	—	2.0	µA	VDD = 2.5V
			—	—	2.2	µA	VDD = 3.0V*
			—	—	9.0	µA	VDD = 5.5V
			—	—	15	µA	VDD = 5.5V Extended Temp.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in Active Operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

NOTES:

N

NOP Instruction 69

O

One-Time-Programmable (OTP) Devices 7
OPTION Instruction 69
OPTION Register 19
Oscillator Configurations 47
Oscillator Start-up Timer (OST) 50

P

Package Marking Information 117
Packaging Information 113
PCL and PCLATH 23
PCON Register 22
PICkit 1 FLASH Starter Kit 79
PICSTART Plus Development Programmer 77
PIE1 Register 21
PIR1 Register 21
Port RB Interrupt 56
PORTA 25
PORTB 28
Power Control/Status Register (PCON) 51
Power-Down Mode (SLEEP) 59
Power-On Reset (POR) 50
Power-up Timer (PWRT) 50
Prescaler 34
PRO MATE II Universal Device Programmer 77
Program Memory Organization 13

Q

Quick-Turnaround-Production (QTP) Devices 7

R

RC Oscillator 48
Reset 49
RETFIE Instruction 70
RETLW Instruction 70
RETURN Instruction 70
RLF Instruction 71
RRF Instruction 71

S

Serialized Quick-Turnaround-Production (SQTP) Devices ... 7
SLEEP Instruction 71
Software Simulator (MPLAB SIM) 76
Software Simulator (MPLAB SIM30) 76
Special Features of the CPU 45
Special Function Registers 17
Stack 23
Status Register 18
SUBLW Instruction 72
SUBWF Instruction 72
SWAPF Instruction 73

T

Timer0
- TIMER0 31
- TIMER0 (TMR0) Interrupt 31
- TIMER0 (TMR0) Module 31
- TMR0 with External Clock 33

Timer1
- Switching Prescaler Assignment 35

Timing Diagrams and Specifications 104
TMR0 Interrupt 56
TRIS Instruction 73
TRISA 25
TRISB 28

V

Voltage Reference Module 43
VRCON Register 43

W

Watchdog Timer (WDT) 58
WWW, On-Line Support 3

X

XORLW Instruction 73
XORWF Instruction 73